



1.0A SURFACE MOUNT SCHOTTKY BRIDGE

Product Summary

V _{RRM} (V)	I ₀ (A)	V _F Max (V) @ +25°C	I _R Max (mA) @ +25°C	
30	1	0.42	1	

Description

Packaged in the compact DFN5060-4 the SDM1L30BLP is designed with low forward voltage and soft switching characteristics to meet the needs of wireless charging applications.

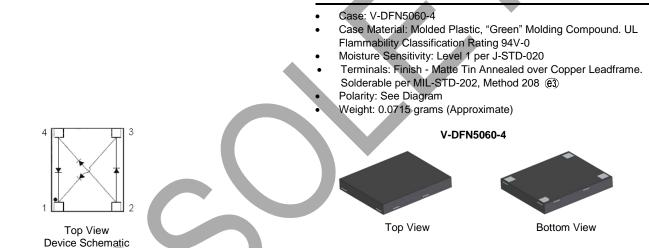
Features

- Low profile package, ideal for thin portable applications
- Low forward voltage drop reduces power dissipation
- Soft switching characteristic ensures that EMI and EFI are minimized
- Guard ring die construction for transient protection
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e.: parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please refer to the related automotive grade (Q-suffix) part. A listing can be found at

https://www.diodes.com/products/automotive/automotiveproducts/.

 This part is qualified to JEDEC standards (as references in AEC-Q) for High Reliability. <u>https://www.diodes.com/quality/product-definitions/</u>

Mechanical Data



Ordering Information (Note 4)

	Part Number	Case	Packaging				
	SDM1L30BLP-13	V-DFN5060-4	3,000/Tape & Reel				
Notes:	lotes: 1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied.						

EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied.
See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.</p>

For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information

Date Code Key			•	S <u>S</u> D3	×	YM = Date Y = Year (e Code Ma ex: C =201					
Year	2014	1	2015		2016	20	17	2018		2019	2	2020
Code	В	В		C D		E		F		G		Н
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D
SDM1L30BLP		1 of 5 December 201										

Document number: DS35906 Rev. 8 - 4

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Maximum Ratings (@TA = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.

Characteristic	Symbol	Value	Unit	
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	Vrrm Vrwm Vrm	30	V	
Average Rectified Output Current	lo	1.0	A	
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load (Per Diode)	IFSM	50	A	

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Typical Thermal Resistance Junction to Case (Note 5)	R _{θJC}	15	°C/W
Operating and Storage Temperature Range	TJ, TSTG	-55 to +150	°C

Electrical Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
Forward Voltage Drop (Per Diode)	VF	-	0.21 0.31	0.42	V	IF = 0.1A, TJ = +25°C IF = 1.0A, TJ = +25°C	
Leakage Current (Note 6) (Per Diode)	IR		_	1.0	mA	V _R = 30V, T _J = +25°C	
Total Capacitance	Ст	_	90	_	pF	$V_{R} = 30V, f = 1.0MHz,$ $T_{J} = +25^{\circ}C$	

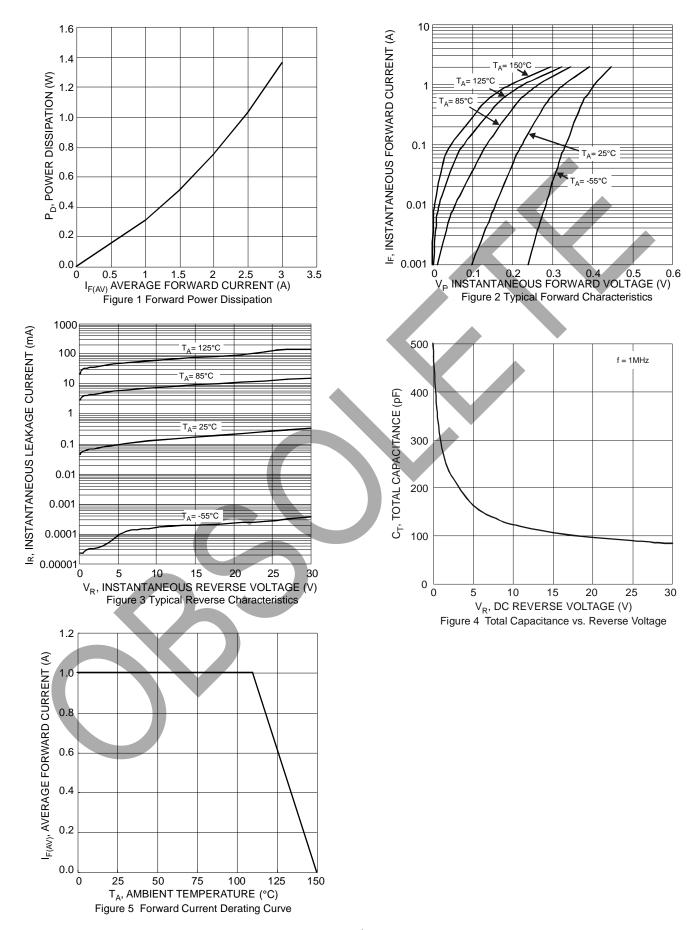
Notes: 5. Device mounted on Polymide PCB with 1x recommended pad layout, with minimum recommended pad layout per http://www.diodes.com. 6. Short duration pulse test used to minimize self-heating effect.





PART OBSOLETE - NO ALTERNATE PART

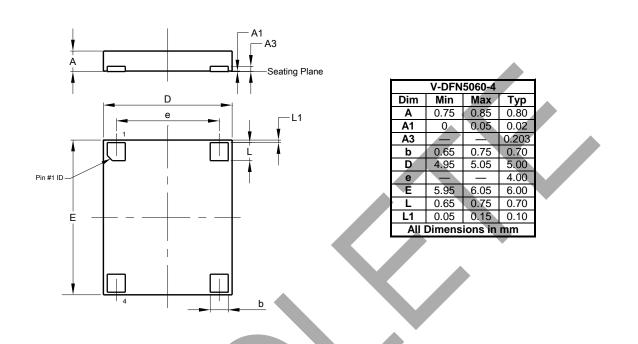
SDM1L30BLP





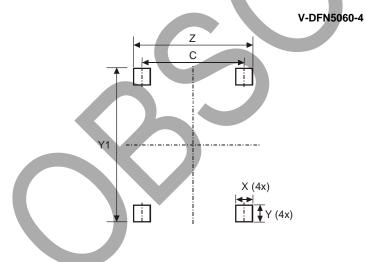
Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.



Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.



Dimonsions	Value (in mm)
Dimensions	value (III IIIII)
С	4.00
Х	0.75
Y	0.95
Y1	6.20
Z	4.75

V-DFN5060-4



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